



Material Content Data Sheet



Sales Product Name		BGA 231N7 E6327		Issued		19. July 2018		
MA#		MA001158790						
Package		PG-TSNP-7-1		Weight*		3.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.114	2.97	2.97	29704	29704
leadframe	non noble metal	zinc	7440-66-6	0.004	0.11		1118	
	non noble metal	tin	7440-31-5	0.005	0.14		1397	
	non noble metal	chromium	7440-47-3	0.006	0.17		1677	
wire	non noble metal	copper	7440-50-8	2.136	55.47	55.89	554684	558876
	noble metal	gold	7440-57-5	0.038	0.98	0.98	9772	9772
encapsulation	organic material	carbon black	1333-86-4	0.006	0.16		1641	
	plastics	epoxy resin	-	0.183	4.76		47602	
	inorganic material	silicondioxide	60676-86-0	1.074	27.90	32.82	279049	328292
leadfinish	non noble metal	tin	7440-31-5	0.111	2.90	2.90	28950	28950
plating	noble metal	silver	7440-22-4	0.104	2.69	2.69	26947	26947
glue	plastics	epoxy resin	-	0.013	0.35		3492	
	noble metal	silver	7440-22-4	0.054	1.40	1.75	13967	17459
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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